

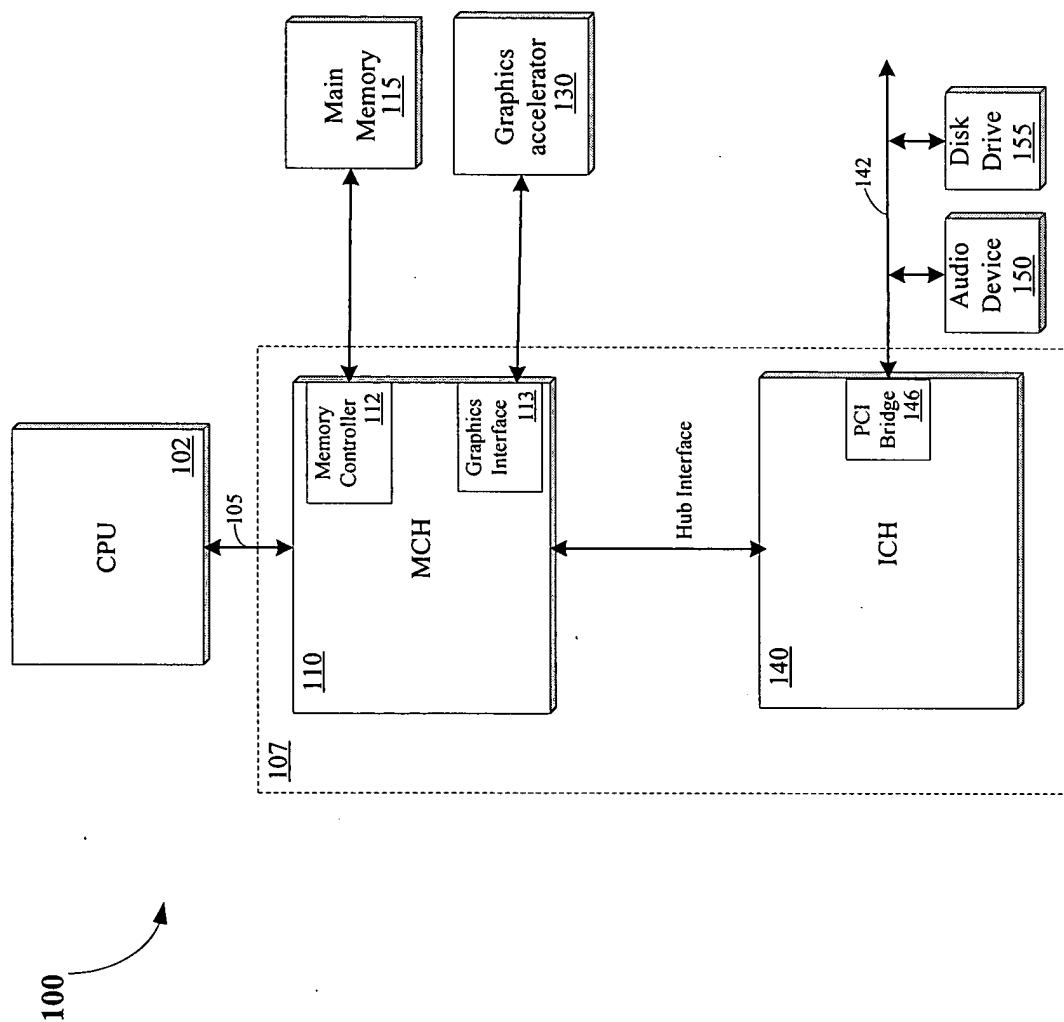
"THERMAL SOLUTION FOR ELECTRONICS COOLING USING  
A HEAT PIPE IN COMBINATION WITH ACTIVE LOOP SOLUTION"

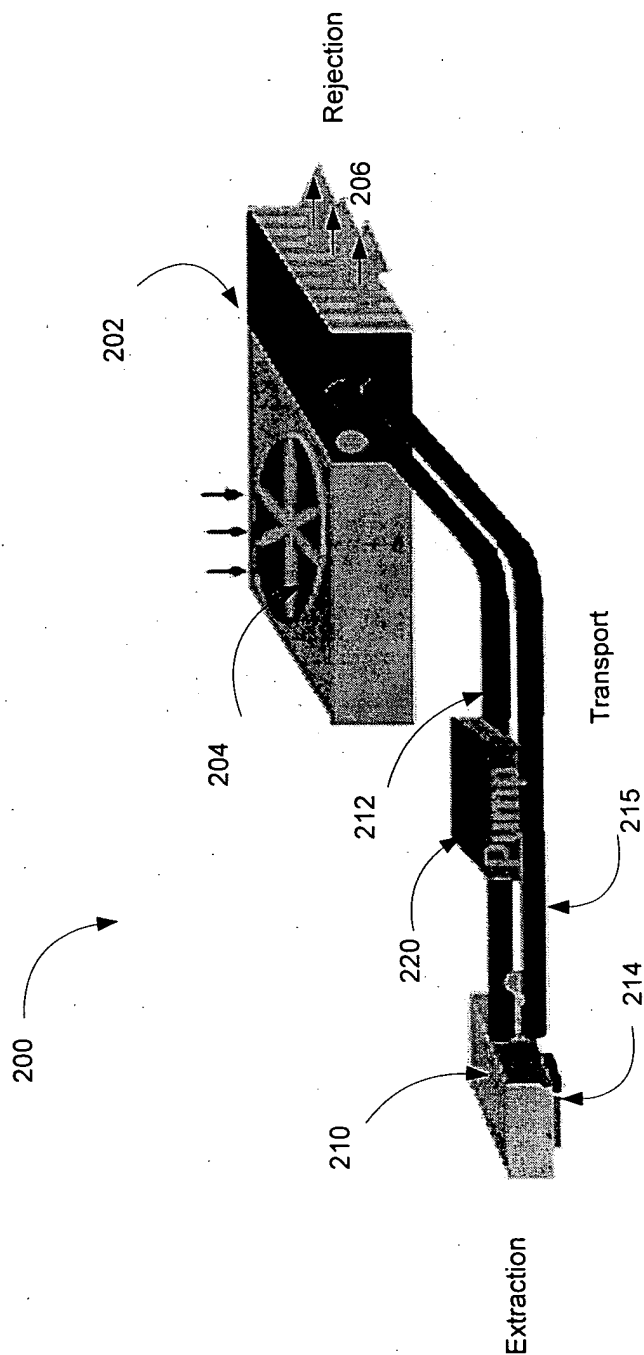
by Eric DiStefano, Himanshu Pokhama

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Sheet 1 of 6

FIG. 1





**FIG. 2**

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Sheet 3 of 6

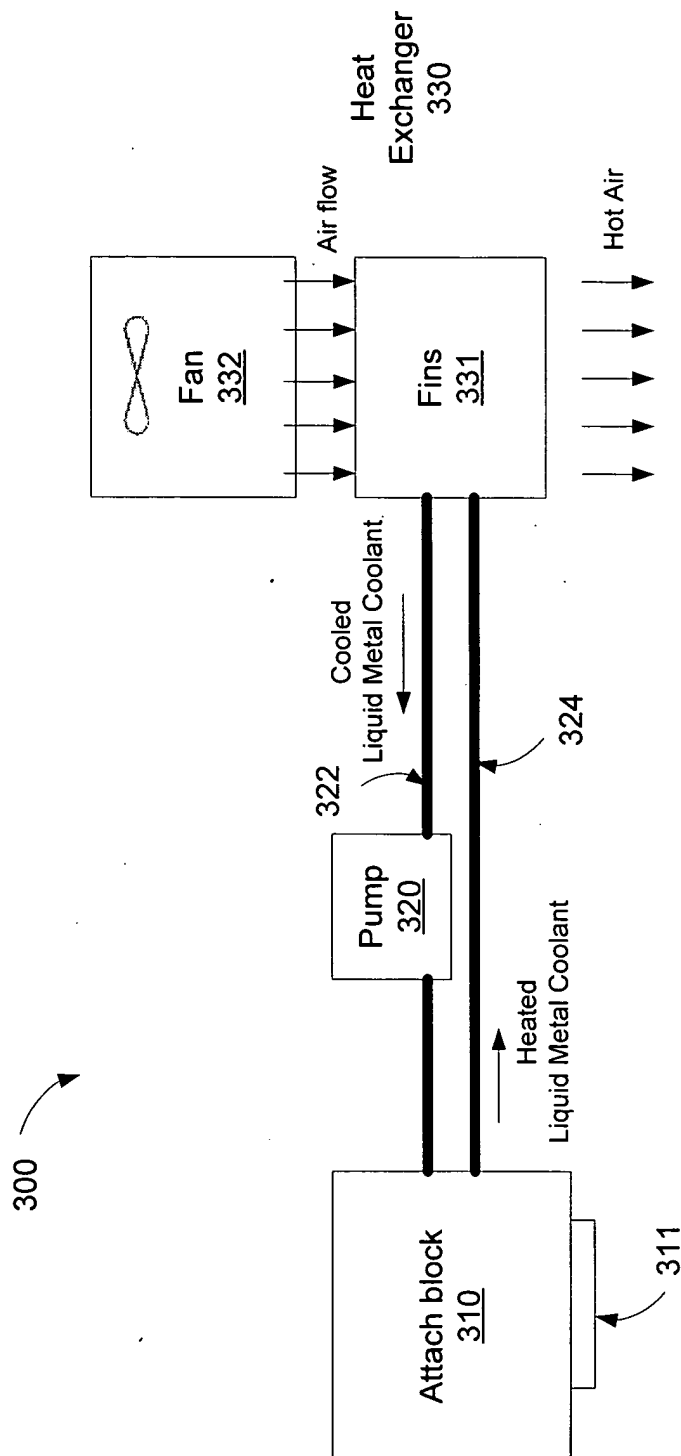


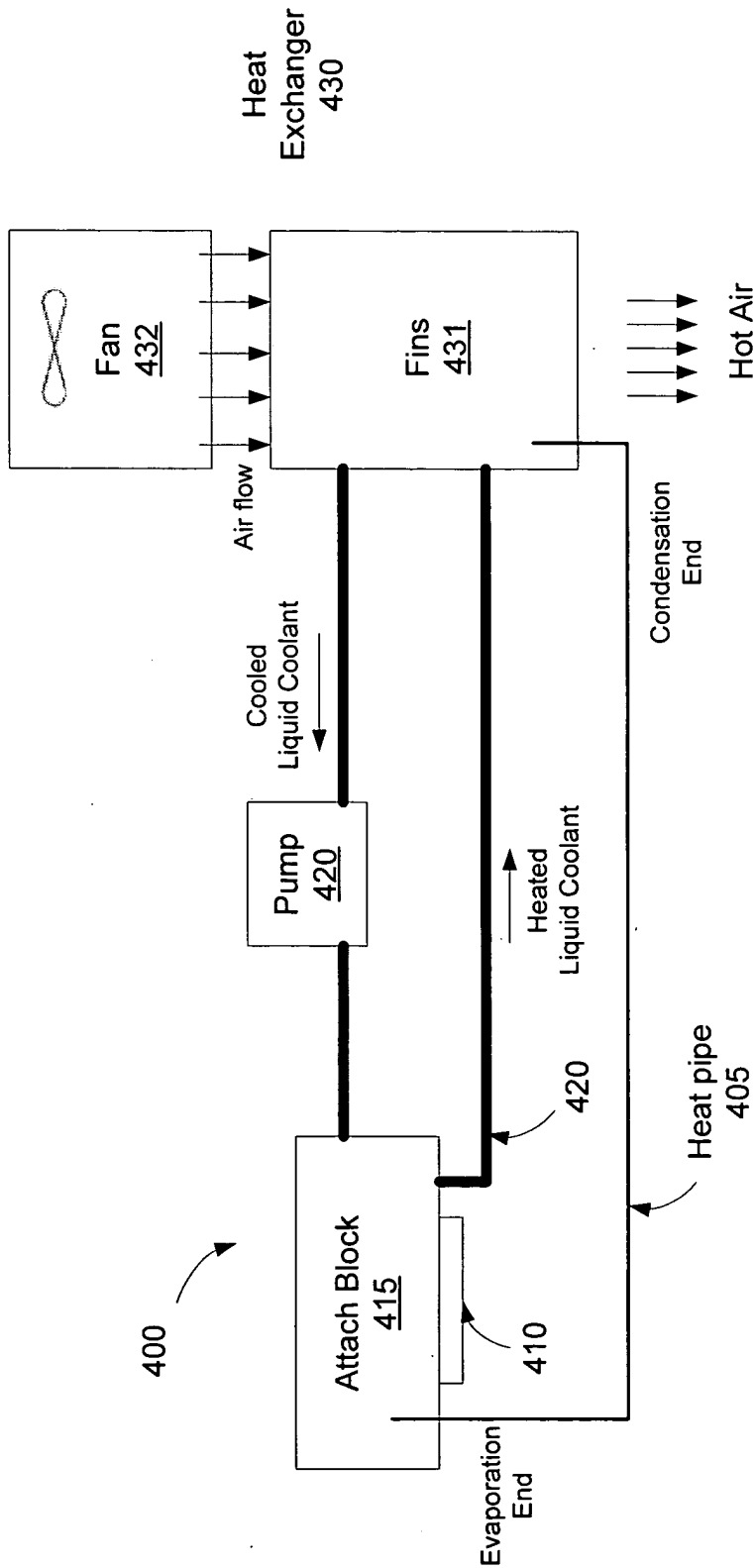
FIG. 3

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Sheet 4 of 6



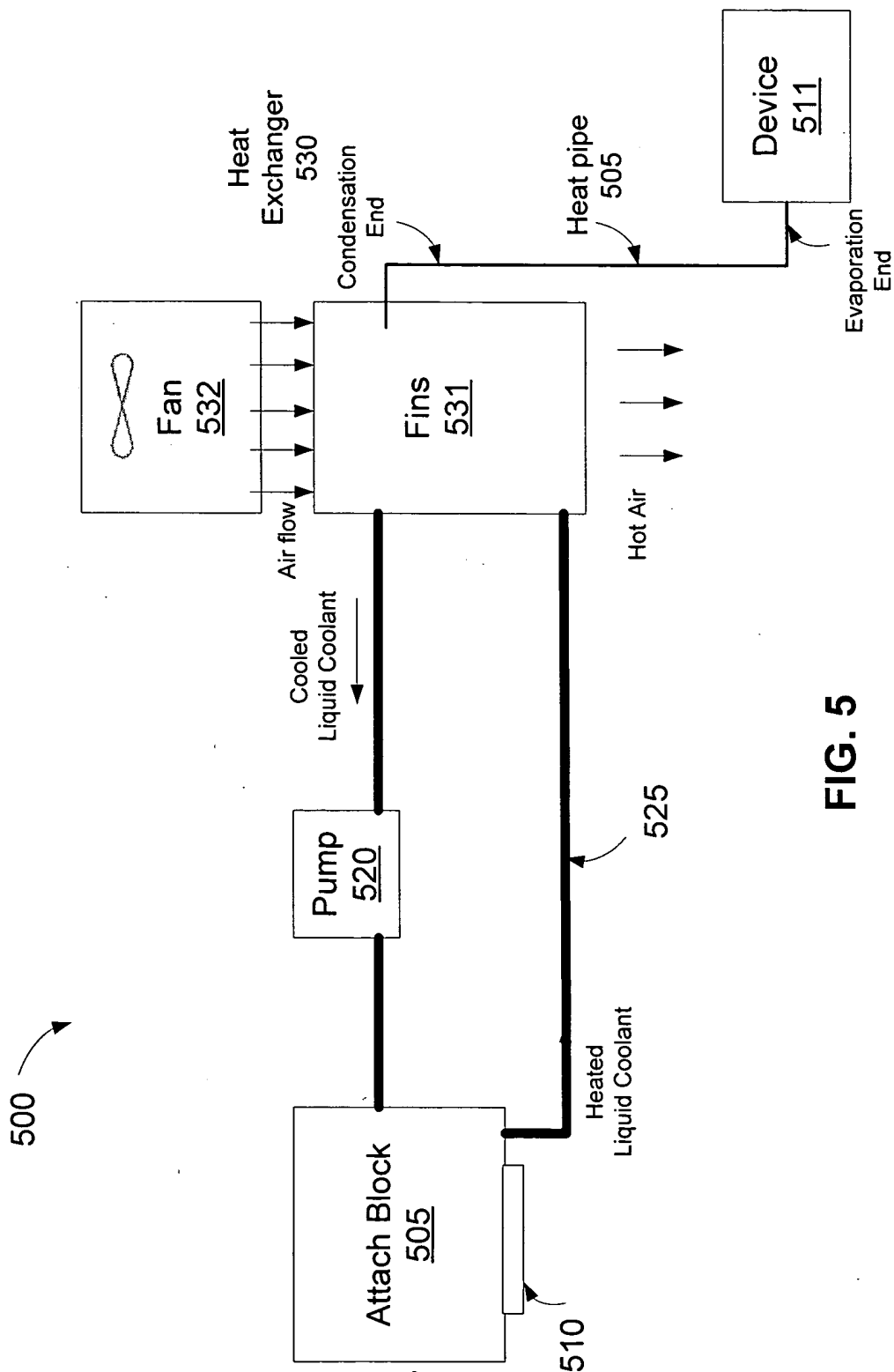
**FIG. 4**

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Sheet 5 of 6



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Sheet 6 of 6

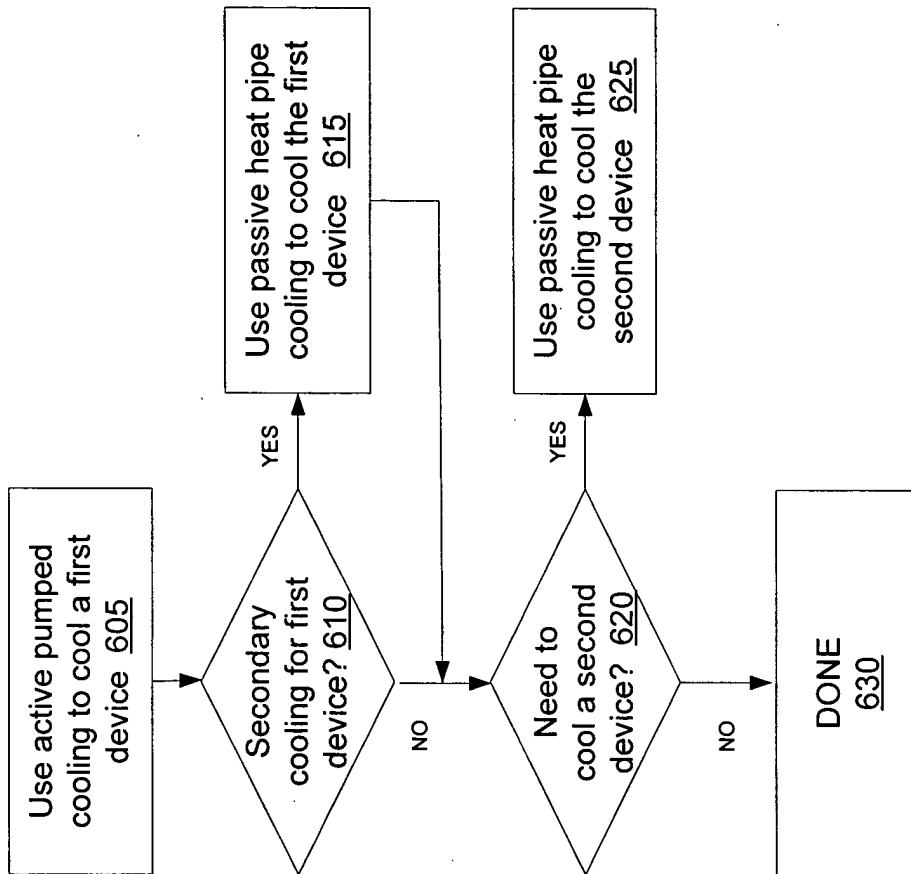


FIG. 6